

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the above-referenced application.

Listing of Claims:

1. (Currently amended) A method of shielding a circuit device, comprising:

- (a) providing a circuit board on which an electronic component has been mounted and which has a ground connection portion;
- (b) inserting an entire portion of said circuit board into a shield pack having a sack shape, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and
- (c) contacting said insulating layer of said shield pack with said electronic component and said circuit board,

wherein said ground connection portion of said circuit board is connected to said electric ~~conductive~~ conductive layer of said shield pack, wherein a ground connection terminal is connected to the ground connection portion, the ground connection terminal including a tip portion and a base portion, the tip portion being inserted through the shield pack, wherein a bottom area of the tip portion is disposed on a surface of the outermost layer and the base portion is disposed within at least the outermost layer, and wherein a sectional area of the base portion is smaller than the bottom area of the tip portion.

2. (Original) The shielding method of a circuit device according to claim 1, wherein said (c) contacting step comprises:

(d) reducing an internal capacity of said shield pack.

3. (Currently amended) The shielding method of a circuit device according to claim 2, wherein

~~said circuit board further comprises a ground connection terminal connected to said ground connection portion, and~~

said ground connection terminal breaks through said shield pack to be connected with said electric conductive layer during said (c) contacting step.

4. (Currently amended) The shielding method of a circuit device according to claim 3, wherein

said ground connection terminal comprises:

[[a]] the tip portion having a conical shape; and

[[a]] the base portion connected to said tip portion, wherein said base portion has a sectional area which is smaller than a bottom plane of said ~~cone~~ conical shape such that said base portion does not project from the bottom plane of said ~~cone~~ conical shape.

5. (Currently amended) The shielding method of a circuit device according to claim 4, wherein

said base portion of said ground connection terminal has a height which is substantially equal to a thickness of said shield pack, and

when said tip portion breaks through said shield pack, the bottom plane of said ~~cone~~ conical shape is connected to said electric conductive layer.

6. (Original) The shielding method of a circuit device according to claim 2, further comprising:
- connecting said ground connection portion and said electric conductive layer by passing an electric conductive connection component through said ground connection portion between said shield pack and said circuit board, after said insulating layer of said shield pack is fit with said electronic component and said circuit board.
7. (Original) The shielding method of a circuit device according to claim 6, wherein said circuit board has a through-hole formed in said ground connection portion,
- said through-hole is filled with an electric conductor connected to said ground connection portion, and
- said connection component passes through said through-hole to connect said ground connection portion with said electric conductive layer.
8. (Previously presented) The shielding method of a circuit device according to claim 6,
- wherein said connection component is used to fix said circuit board contained within said shield pack to a housing, and
- said housing has an electric conductive portion connected to said electric conductive layer.
9. (Previously presented) The shielding method of a circuit device according to claim 3,
- wherein said (d) reducing step comprises:
- vacuum-sucking air contained in said shield pack such that said insulating layer of said shield pack contacts said electronic component and said circuit board.

10. (Previously presented) The shielding method of a circuit device according to claim 3,
wherein an adhesive agent is coated on at least a portion of said circuit board and at least
a portion of an outer surface of said electronic component, and

said (d) reducing step comprises:

vacuum-sucking air contained in said shield pack such that said insulating layer of
said shield pack contacts said electronic component and said circuit board.

11. (Previously presented) The shielding method of a circuit device according to claim 3,
wherein said shield pack is made of thermal shrinkage material, and

said (d) reducing step comprises:

heating said shield pack such that said insulating layer of said shield pack contacts
said electronic component and said circuit board.

12. (Previously presented) The shielding method of a circuit device according to claim 3,
wherein an adhesive agent is coated on at least a portion of said circuit board and at least
a portion of an outer surface of said electronic component,

said shield pack is made of thermal shrinkage material, and

said (d) reducing step comprises:

heating said shield pack such that said insulating layer of said shield pack contacts
said electronic component and said circuit board.

13. (Currently amended) An electromagnetically shielded circuit device, comprising:

a circuit board on which an electronic component has been mounted and which has a ground connection portion;

a sack-shaped shield pack which covers an entire portion of said circuit board, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and

an electric conductive connection component which passes through said shield pack to said circuit board to connect said ground connection portion to said electric ~~conductor~~ conductive layer of said shield pack, wherein said electric conductive connection component includes a tip portion and a base portion, the tip portion being insertable through the shield pack, wherein a bottom area of the tip portion is disposed on a surface of the outermost layer and the base portion is disposed within at least the outermost layer, and wherein a sectional area of said base portion is smaller than the bottom area of the tip portion.

14. (Original) The electromagnetically shielded circuit device according to claim 13, wherein

said connection component is a ground connection terminal which is previously fixedly provided to said ground connection portion of said circuit board.

15. (Currently amended) The electromagnetically shielded circuit device according to claim 14, wherein said ground connection terminal includes ~~has a~~ the tip portion having a conical shape and ~~[[a]]~~ the base portion connected to said tip portion, and
- said base portion has a sectional area which is smaller than a bottom plane of said ~~cone~~ conical shape such that said base portion does not project from the bottom plane of said ~~cone~~ conical shape.
16. (Currently amended) The electromagnetically shielded circuit device according to claim 15, wherein said base portion of said ground connection terminal has a height which is substantially equal to a thickness of said shield pack, and
- the bottom plane of said ~~cone~~ conical shape is connected to said electric conductive layer under in a state that said tip portion breaks through said shield pack.
17. (Original) The electromagnetically shielded circuit device according to claim 13, wherein said circuit board has a through-hole formed in said ground connection portion,
- said through-hole is filled with an electric conductor connected to said ground connection portion, and
- said connection component passes through said through-hole to connect said ground connection portion with said electric conductive layer.

18. (Currently amended) The electromagnetically shielded circuit device according to claim 13, wherein said connection component is a ~~vis~~ via, and is used to fix said circuit board contained within said shield pack to a housing, and
said housing has an electric conductive portion connected to said electric conductive layer.

19. (New) A method of shielding a circuit device, comprising:

providing a circuit board on which an electronic component is mounted and which has a ground connection portion;

inserting a portion of said circuit board into a shield pack, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and

contacting said insulating layer of said shield pack with said electronic component and said circuit board,

wherein said ground connection portion of said circuit board is connected to said electric conductive layer of said shield pack, and a ground connection terminal is connected to the ground connection portion, said ground connection terminal including:

a tip portion having a conical shape; and

a base portion connected to said tip portion, wherein said base portion has a sectional area which is smaller than a bottom area of said conical shape such that said base portion does not project from the bottom area of said conical shape

20. (New) An electromagnetically shielded circuit device comprising:

a circuit board on which an electronic component is mounted and which has a ground connection portion;

a shield pack which covers a portion of said circuit board, said shield pack having an insulating layer as an innermost layer and an electric conductive layer as an outermost layer; and

an electric conductive connection component which passes through said shield pack to said circuit board to connect said ground connection portion to said electric conductive layer of said shield pack,

wherein a ground connection terminal is connected to said ground connection portion, said ground connection terminal including:

a tip portion having a conical shape; and

a base portion connected to said tip portion, said base portion having a sectional area which is smaller than a bottom area of said conical shape such that said base portion does not project from the bottom area of said conical shape.